

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10666930				
<b>Filing Date:</b>	19-Sep-2003				
<b>Title of Invention:</b>	Method and apparatus for supporting wafers for die singulation and subsequent handling				
<b>First Named Inventor/Applicant Name:</b>	Warren M. Farnworth				
<b>Filer:</b>	Jason Nixon/Debra Mitchell				
<b>Attorney Docket Number:</b>	2269-5529US (02-0766.00/U)				
Filed as Large Entity					
<b>Utility Filing Fees</b>					
<b>Description</b>		<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>					
<b>Pages:</b>					
<b>Claims:</b>					
<b>Miscellaneous-Filing:</b>					
<b>Petition:</b>					
<b>Patent-Appeals-and-Interference:</b>					
<b>Post-Allowance-and-Post-Issuance:</b>					
<b>Extension-of-Time:</b>					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>